

Die Attach Adhesive

Image Sensor Attach



Application 應用	Product 產品	Viscosity黏度 (cps @ 25°C)	T.I 觸變值	Tg(°C) 玻璃轉化溫度	Hardness硬度 (Shore D)	Work Life 工作時間 (Days)	Cure condition 固化條件	Characteristic 特性
Image sensor die attach bonding	DA-4001F	20,000	3.3	55	83	1.5	Convection Oven 5m @ 150°C or Hot Plate 2m @ 120°C	High modulus, Good Adhesion
	DA-4001G	20,000	3.3	55	83	1.5	Convection Oven 5m @ 150°C or Hot Plate 2m @ 120°C	High modulus, Good Adhesion
	DA-4001M	38,000	4.7	43	86	3	Convection Oven 10m @ 150°C or Hot Plate 2m @ 120°C	Low tilt
	DA-4013	16,000	5	4	87	1	Convection Oven 15m @ 150°C	Low viscosity
	DA-4013W	14,000	5	49	92	1	Convection Oven 15m @ 150°C	White color version of DA-4013
	DA-4051	14,000	2.6	42	80	3	Convection Oven 30m @ 85°C or Hot Plate 2m @ 120°C	Low tilt, Low warpage
	DA-4051L	8,000	3.8	32	78	3	Hot Plate 2m @ 120°C	Low warpage, Low viscosity, High adhesion
	DA-4051FC	17,500	5.5	31	75	3	Hot Plate 2m @ 100°C	Low warpage, Fast cure
	DA-4051FC(R2)	20,000	6	35	77	3	Convection Oven 30m @ 70°C or Hot Plate 1m @ 100°C or Hot Plate 2m @ 80°C	Lower RBO than DA-4051FC
	DA-4051FL	7,000	2.8	27	80	3	Hot Plate 2m @ 120°C	Low warpage, Low viscosity, Fast cure
	DA-4051L(P)	8,100	3.6	38	75	3	Hot Plate 2m @ 100°C	Pink color of DA-4051L
	DA-4055	37,000	6.1	23	68	3	Hot Plate 2m @ 100°C	Fast curable, Low warpage, Low Tilt
	DA-4100	2,200 (100rpm)	3.4	24	85	3	Hot Plate 2m @ 120°C	Self leveling
	DA-4100(S25)	2,400 (100rpm)	3.2	24	82	3	Hot Plate 2m @ 120°C	Self leveling, Low Warpage with 25µm polymer spacer
	DA-4052	15,900	5.3	39	66	3	Hot Plate 2m @ 100°C	Low warpage, Higher adhesion than DA-4051FC
DA-4057	8,600	3.2	46	75	3	Hot Plate 2m @ 100°C	Low RBO of DA-4051L	